

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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HI1206T161R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

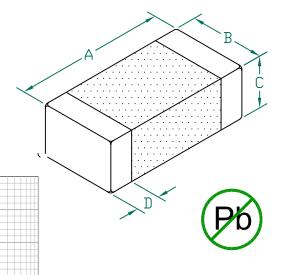
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- 3A

250

IMPEDANCE

D 0.51 [.020] ± 0.25 [.010]



ELECTRICAL CHARACTERISTICS:								
Z @ 100MHz (Ω)		DCR (Ω)	Rated Current					
Nominal	160							
Minimum	120							
Maximum	208	0.018	6000 mA					

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 2000 PCS/REEL, EMBOSSED PLASTIC TAPE.
- 2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 3. TERMINATION FINISH IS 100% TIN.
- 4. OPERATEING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

FREQUENCY (MHz)

100

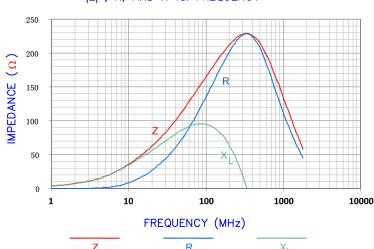
1000

10000

Z vs FREQUENCY

IMPEDANCE UNDER DC BIAS

|Z| , R, AND X vs. FREQUENCY



2.06 [.081] 4.65 [.183]

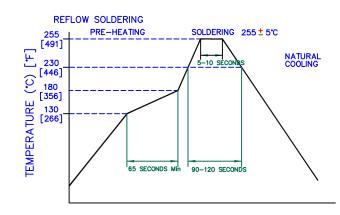
(For wave soldering, add 0.762 [0.030] to this dimension)

LAND PATTERNS FOR REFLOW SOLDERING

1.13

[.044]

RECOMMENDED SOLDERING CONDITIONS





	This print is			
н	OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13		Tech, and is subject to re and with the
G	UPDATE CURVES AND REF NUMBER	07/08/10	JUN	no copies sh the written o
F	UPDATE COMPANY LOGO	10/09/08	ТМВ	All rights to
Е	ADD EMBOSSED PLASTIC TAPE TO NOTE 1	01/19/07	JRK	are reserved. PROJECT/PART NU
D	CHANGE C DIMENSION	01/15/07	JRK	
С	CHG REEL QTY ADD ROHS SYMBOL	08/28/06	JRK	HI1206
В	CHANGE MAXIMUM IMPEDANCE FROM 200	01/11/05	JRK	DATE: 01 /1
Α	ORIGINAL DRAFT	01/13/04	JRK	01/1

DESCRIPTION

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DRAWN BY

reserved.	I		
ECT/PART NUMBER:	REV	PART TO	PE
HI1206T161R-10	Н	CO-	-F
: 01/17/04 S	CALE: N	7	Г

01/13/04 SCALE: NTS SHEET:

HI1206T161R-10-H TOOL # _ 1 of 1

AGILENT E4991A RF Impedance/Material Analyzer HP 16194A Test Fixture. TEST REF. 6308